


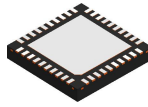
DATA BOOK PACKAGE OUTLINE

LEADFRAME EXAMPLE

4212992

DRAFTER: T. LEQUANG	DATE: 08/25/2016		DIMENSIONS IN MILLIMETERS
DESIGNER:	DATE:	 TEXAS INSTRUMENTS <small>SEMICONDUCTOR OPERATIONS</small>	
CHECKER: K. SINCERBOX & V. PAKU	DATE: 08/01/2016		
ENGINEER: B. TAN	DATE: 08/23/2016		
APPROVED: E. REY & D. CHIN	DATE: 08/23/2016		
RELEASED: WDM	DATE: 08/25/2016		
<p style="text-align: center; font-size: 1.2em; margin: 0;">ePOD, RSB0040A / WQFN, 40 PIN, 0.4 MM PITCH</p>		<small>CODE IDENTITY NUMBER</small> 01295	
TEMPLATE INFO: EDGE# 4218519	DATE: 03/20/2013	SCALE 12X	SIZE A
		4215000	<small>REV</small> A
		<small>PAGE</small> 1 OF 5	

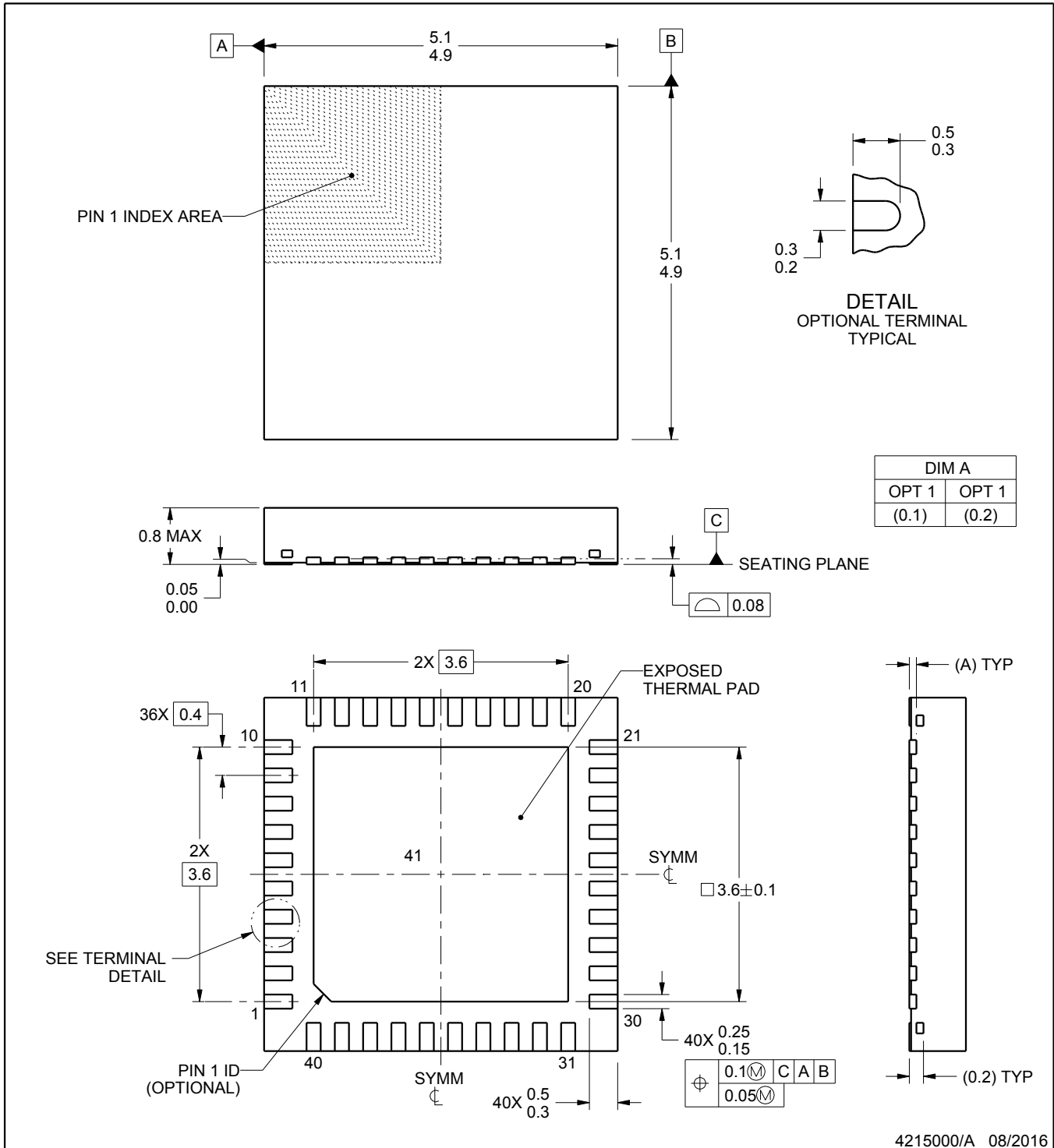
RSB0040A



PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



4215000/A 08/2016

NOTES:

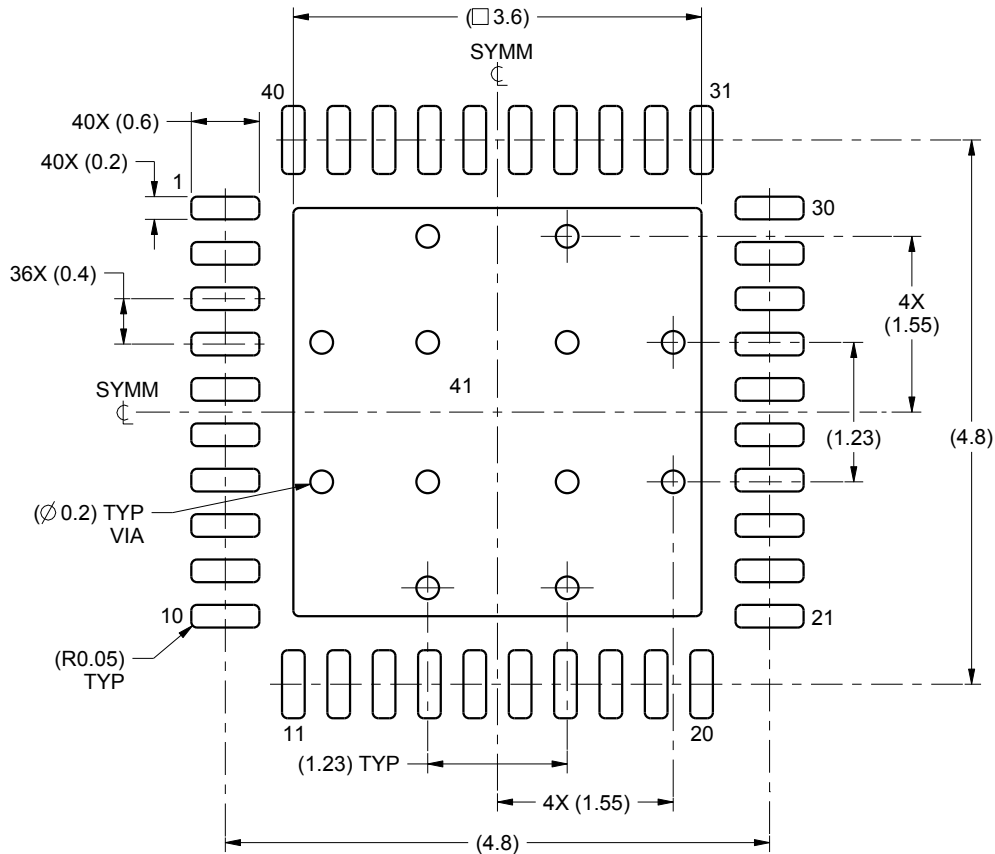
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

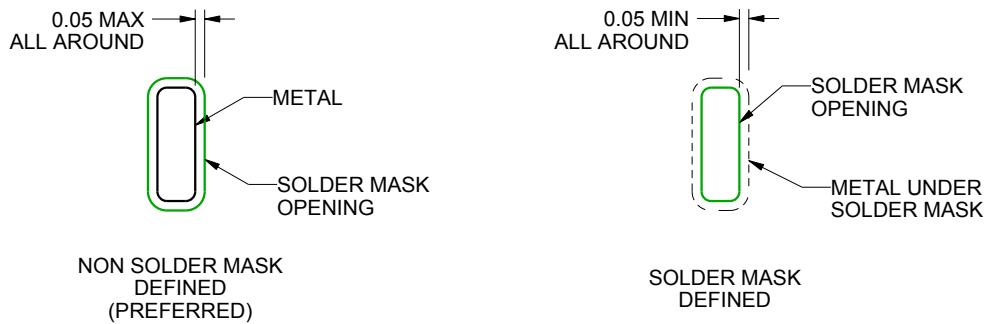
RSB0040A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

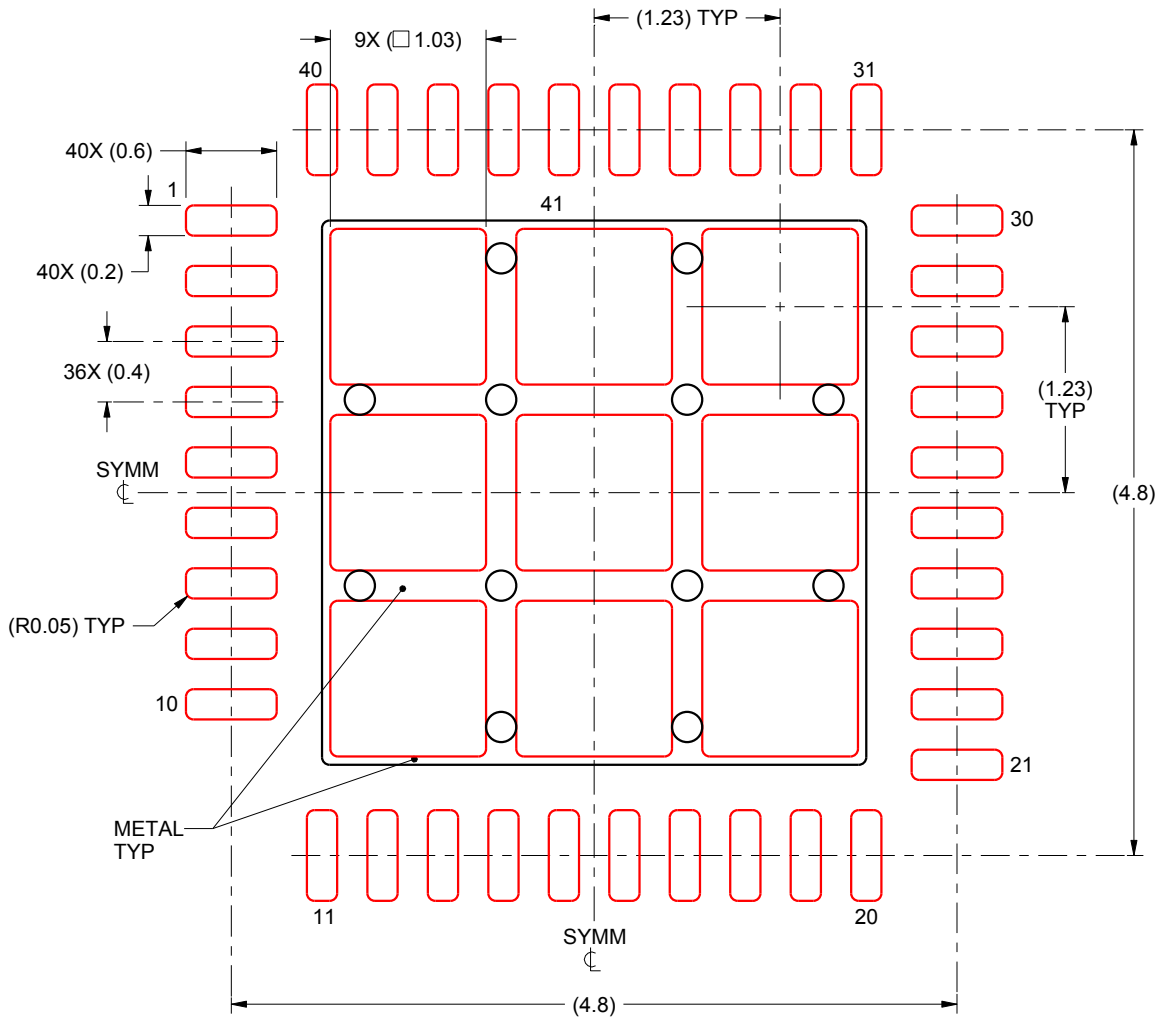
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sl原因271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RSB0040A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 41
73.7% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTSMAN
A	RELEASE NEW DRAWING	2159488	08/25/2016	B. TAN / T. LEQUANG